



Product Change Notification

108934 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

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Product Change Notification

Change Notification #: 108934 - 00
Change Title: Land Grid Array (LGA) Microprocessor, LGA771/LGA775/FC-LGA6 Cover Removal, PCN 108934-00, Product Material
Date of Publication: November 14, 2008

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Jan 07, 2009
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Description of Change to the Customer:

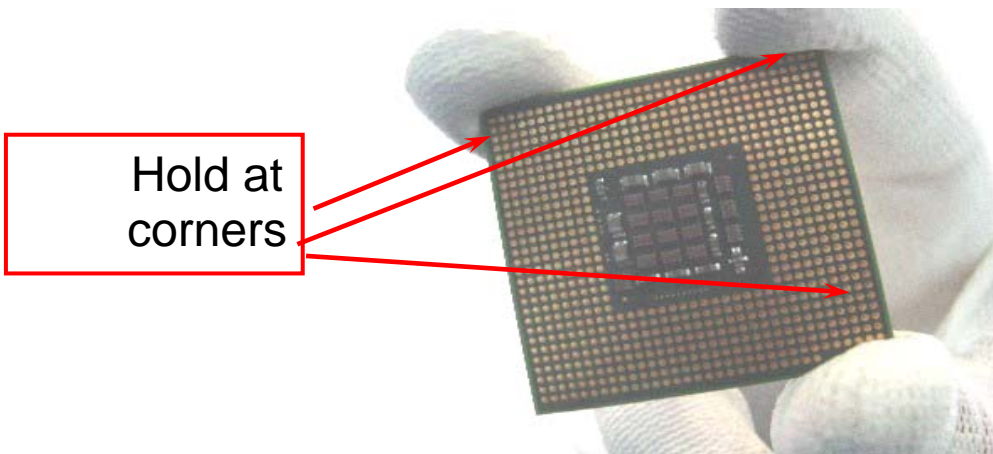
In an effort to reduce an impact to the environment and minimize the handling of the microprocessor, Intel® is eliminating the land side cover from all LGA771, LGA775, and FC-LGA6 microprocessors (37.5x37.5mm substrate size). This includes all future LGA771/LGA775/FC-LGA6 microprocessors. Shipments may contain a mixture of products including those with covers and those that are coverless.

Customer Impact of Change and Recommended Action:

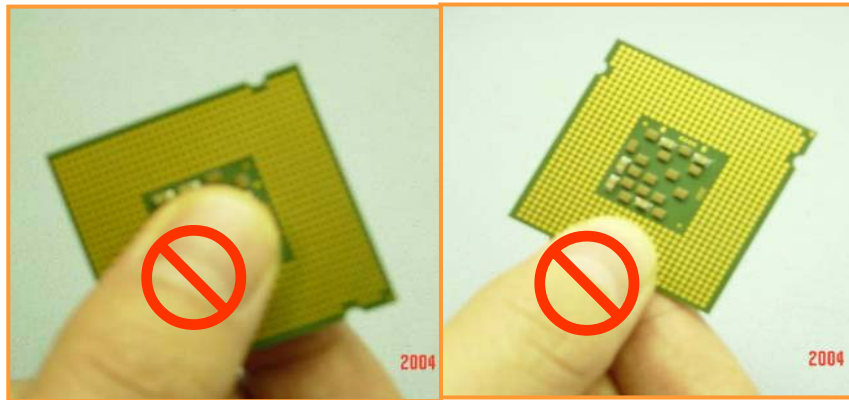
Intel anticipates no impact to customers. Intel recommends the following actions: notify your receiving department of the change; use the Handling Precautions without LGA Covers guidelines for the handling procedure detailed in this PCN. Customers may continue to receive microprocessors with covers until existing inventory is depleted. See processor and LGA cover photos below.

Handling Precautions without LGA Covers

For coverless product handling, follow the same handling guidelines used after the cover has been removed. All chip handling procedures should be adhered to.

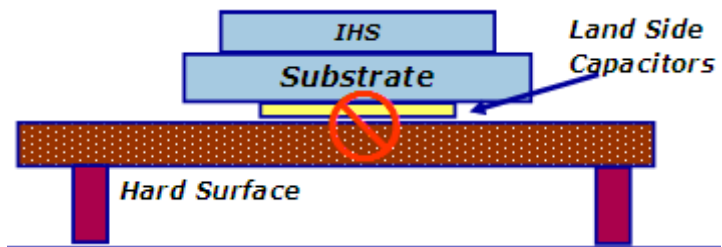


Do not touch land side capacitors or gold land pads.

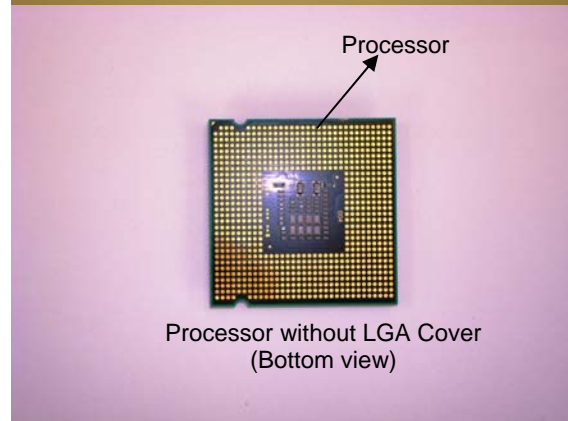
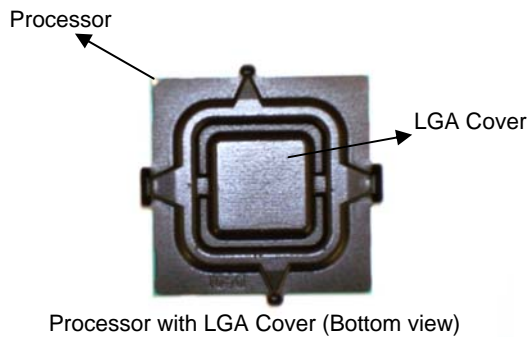
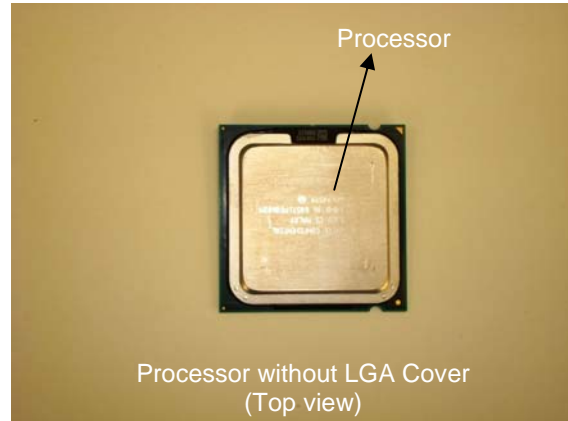
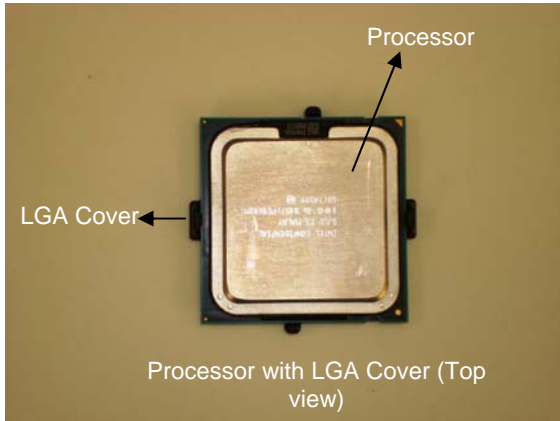
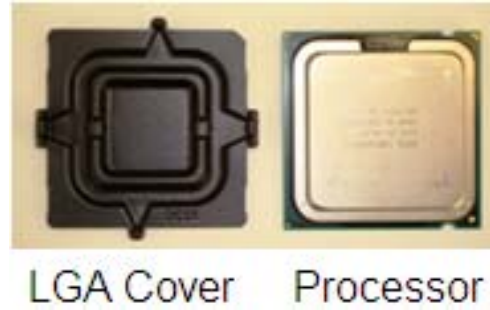
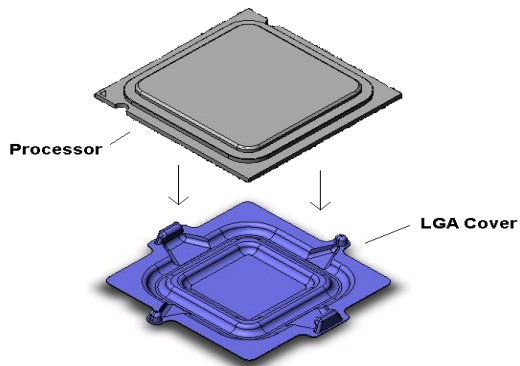


Avoid placing the microprocessor on a hard surface with land side capacitors down.

Leave in shipping tray when not in use.



Note: Intel highly recommends scrapping any units that have been dropped or mishandled.



Products Affected / Intel Ordering Codes:

All LGA771, LGA775 and FC-LGA6 microprocessors (37.5x37.5mm substrate size).

Reference Documents / Attachments:

Document:

Location #:

PCN Revision History:

Date of Revision:
November 14, 2008

Revision Number:
00

Reason:
Originally Published PCN